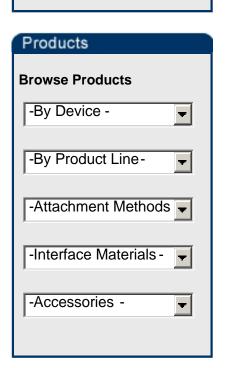
# Quick Reference Search by part # **Check distributor** part inventory



#### **Useful Links**

Building a part # Part # Cross Ref

MSDS Safety Sheets How to order? Find Sales Rep Find Distributor Sample Request **Quote Request** Catalog Request

## Solder Anchor Attachment Method

▶ Products ▶ Design Resources ▶ Technical Info ▶ Global Sales ▶ News/Events

Part Number: 10 - THMA - 01G

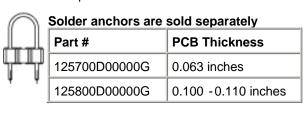
RoHS √ Compliant Printer Friendly Version Download our BGA Brochure (PDF)

| BGA Surface | Interface   | Heat Sink Finish |  |
|-------------|-------------|------------------|--|
| *Flip Chip  | <u>T710</u> | Black Anodize    |  |

\*Includes foam pad around perimeter that stabilizes the part so heat sink does not move.

### **Features and Benefits**

- Solder Anchors provide the most rugged mounting in the industry
- Simple tool -free installation
- Minimal PC Board real estate is required for mounting
- lip design allows for easy removal in case of rework
- -directional airflow to maximize Pin Fin array allows omni heat dissipation



2 Solder anchors must be soldered to the PCB Prior to attaching the heat sink clip. View Datasheet

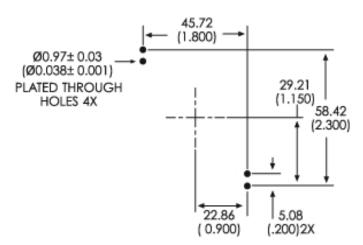
| Width | Length | Height | Fin<br>Thickness<br>Across<br>Width | Fin<br>Thickness<br>Across<br>Length | Base<br>Thickness | # of fins<br>across<br>width | # of fins<br>across<br>length |
|-------|--------|--------|-------------------------------------|--------------------------------------|-------------------|------------------------------|-------------------------------|
| 31mm  | 34.9mm | 35mm   | 1.52mm                              | 3.81mm                               | 3.81mm            | 6                            | 6                             |

## Mechanical Outline Drawing

10-thma-01G BGA Heat Sink Dra

 $\pm 0.38(\pm .015)$ Unless otherwise shown, tolerances are

## Recommended PCB Hole Pattern



## **Thermal Performance**

\* ? n \*\* ? f 10.7 3.95

10-thma-01G BGA Heat Sink Thermal (

- \* Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.
- \*\* Forced convection thermal resistance based on an entering 1.0 m/s (200 lfm) airflow. Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.

This data sheet represents only one of a broad range of products we make to cool electronics. Our representatives can help you configure a complete cooling solution for your individual applications.

For more information on how to put our strengths to work for you, contact your local sales representative:

http://www.aavidthermalloy.com/sales/reps.shtml